



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

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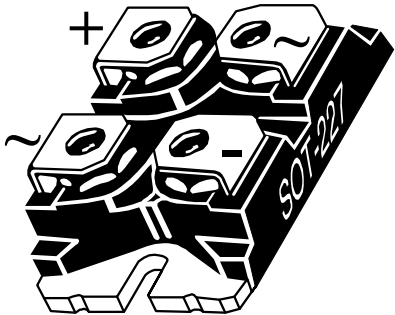
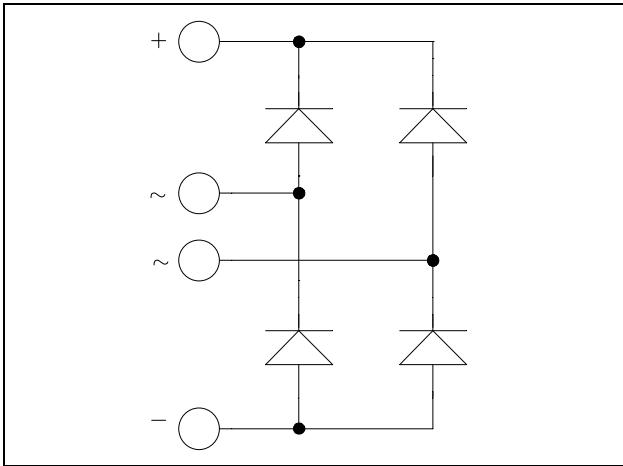
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ISOTOP[®] Fast Diode Full Bridge Power Module

$V_{RRM} = 200V$
 $I_F = 60A @ T_c = 80^{\circ}C$



Application

- Switch mode power supplies rectifier
- Induction heating
- Welding equipment
- High speed rectifiers

Features

- Ultra fast recovery times
- Soft recovery characteristics
- High blocking voltage
- High current
- Low leakage current
- Very low stray inductance
- High level of integration
- ISOTOP[®] Package (SOT-227)

Benefits

- Outstanding performance at high frequency operation
- Low losses
- Low noise switching
- Direct mounting to heatsink (isolated package)
- Low junction to case thermal resistance
- RoHS Compliant

Absolute maximum ratings

Symbol	Parameter	Max ratings	Unit		
V_R	Maximum DC reverse Voltage	200	V		
V_{RRM}	Maximum Peak Repetitive Reverse Voltage				
$I_{F(AV)}$	Maximum Average Forward Current	Duty cycle = 50%	$T_c = 25^{\circ}C$	90	A
			$T_c = 80^{\circ}C$	60	
I_{FSM}	Non-Repetitive Forward Surge Current	8.3ms	$T_j = 45^{\circ}C$	500	

CAUTION: These Devices are sensitive to Electrostatic Discharge. Proper Handling Procedures Should Be Followed. See application note APT0502 on www.microsemi.com

All ratings @ $T_j = 25^\circ\text{C}$ unless otherwise specified

Electrical Characteristics

Symbol	Characteristic	Test Conditions	Min	Typ	Max	Unit
V_F	Diode Forward Voltage	$I_F = 60\text{A}$		1.1	1.15	V
		$I_F = 120\text{A}$		1.4		
		$I_F = 60\text{A}$	$T_j = 125^\circ\text{C}$	0.9		
I_{RM}	Maximum Reverse Leakage Current	$V_R = 200\text{V}$	$T_j = 25^\circ\text{C}$		250	μA
			$T_j = 125^\circ\text{C}$		500	
C_T	Junction Capacitance	$V_R = 200\text{V}$		210		pF

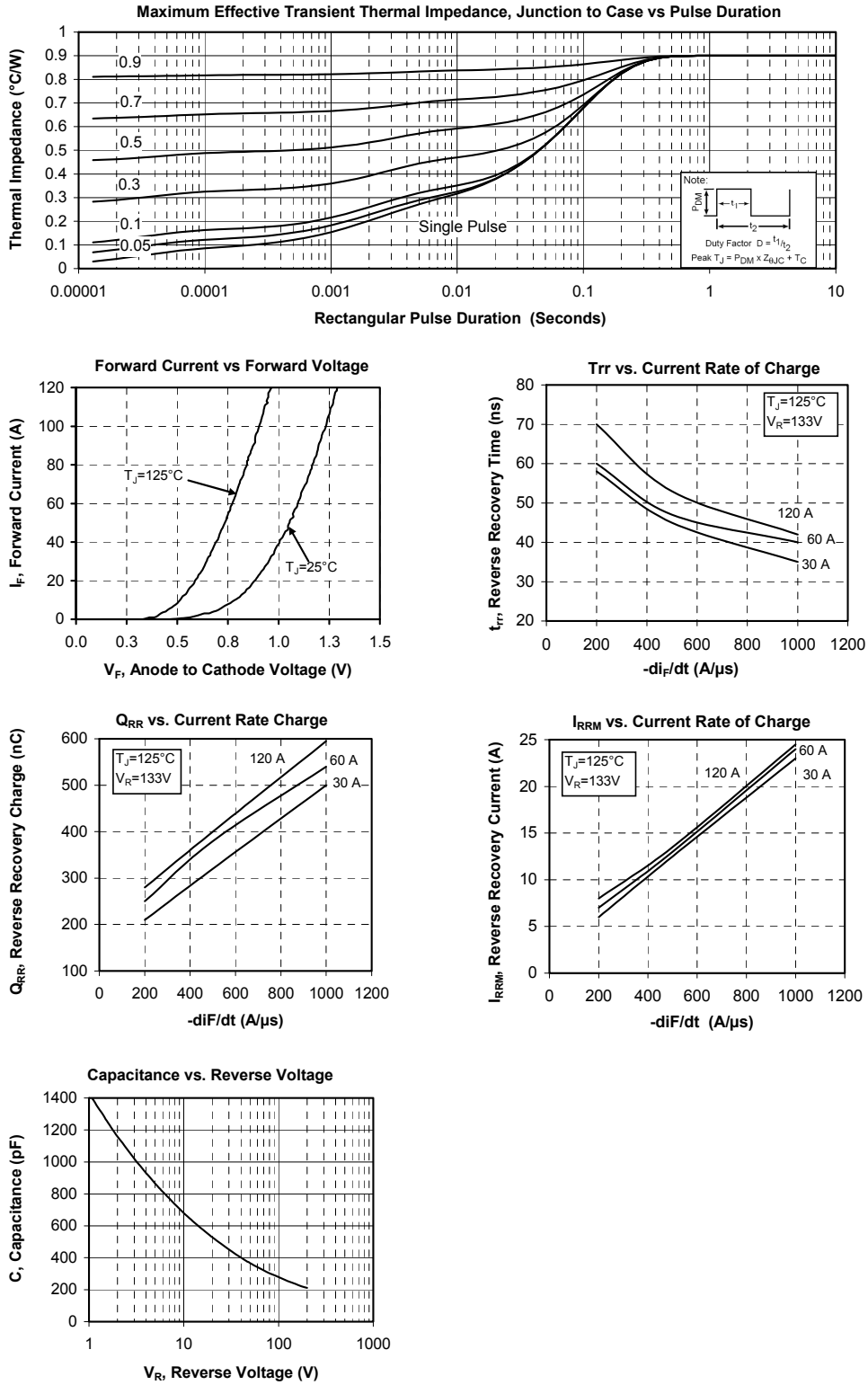
Dynamic Characteristics

Symbol	Characteristic	Test Conditions	Min	Typ	Max	Unit
t_{rr}	Reverse Recovery Time	$I_F = 60\text{A}$ $V_R = 133\text{V}$ $di/dt = 200\text{A}/\mu\text{s}$	$T_j = 25^\circ\text{C}$		31	ns
			$T_j = 125^\circ\text{C}$		60	
Q_{rr}	Reverse Recovery Charge		$T_j = 25^\circ\text{C}$		60	nC
			$T_j = 125^\circ\text{C}$		250	
I_{RRM}	Reverse Recovery Current		$T_j = 25^\circ\text{C}$		3	A
			$T_j = 125^\circ\text{C}$		7	
t_{rr}	Reverse Recovery Time	$I_F = 60\text{A}$ $V_R = 133\text{V}$ $di/dt = 1000\text{A}/\mu\text{s}$	$T_j = 125^\circ\text{C}$		40	ns
Q_{rr}	Reverse Recovery Charge				540	nC
I_{RRM}	Reverse Recovery Current				24	A

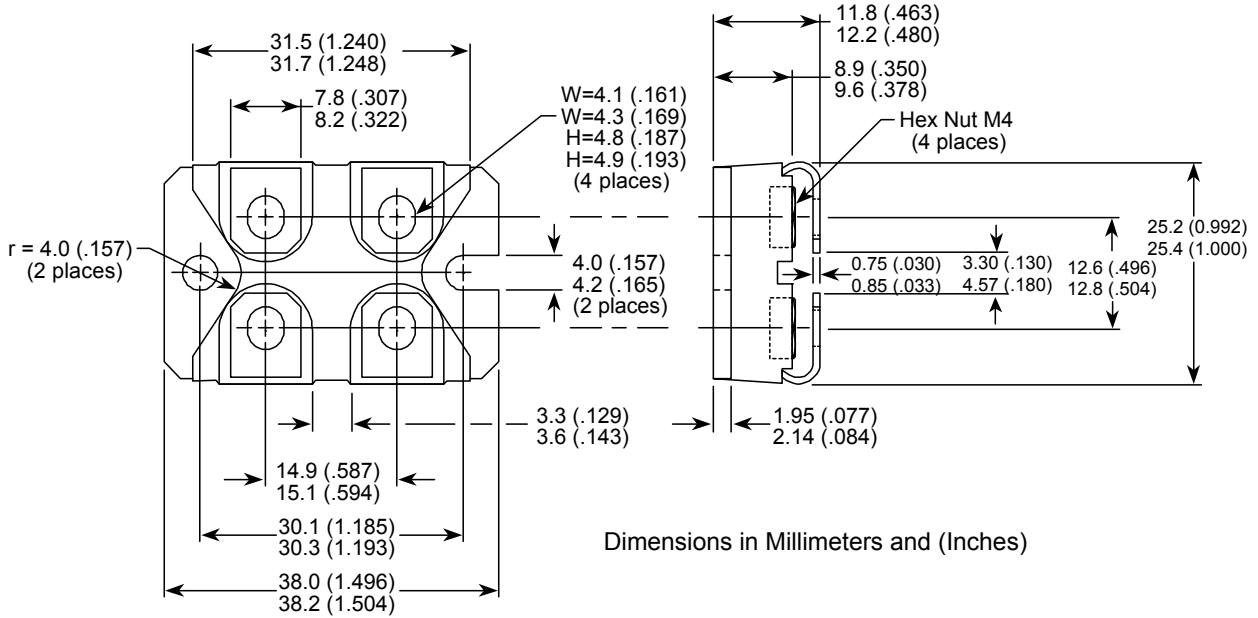
Thermal and package characteristics

Symbol	Characteristic	Min	Typ	Max	Unit
R_{thJC}	Junction to Case Thermal resistance			0.9	$^\circ\text{C}/\text{W}$
R_{thJA}	Junction to Ambient			20	
V_{ISOL}	RMS Isolation Voltage, any terminal to case $t = 1\text{ min}$, 50/60Hz	2500			V
T_j, T_{STG}	Storage Temperature Range	-55		150	$^\circ\text{C}$
T_L	Max Lead Temp for Soldering: 0.063" from case for 10 sec			300	
Torque	Mounting torque (Mounting = 8-32 or 4mm Machine and terminals = 4mm Machine)			1.5	N.m
Wt	Package Weight		29.2		g

Typical Performance Curve



SOT-227 (ISOTOP[®]) Package Outline



ISOTOP[®] is a registered trademark of ST Microelectronics NV

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